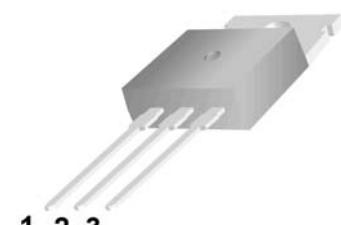
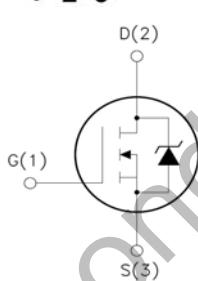


 <b>WGP4N70SE</b>	<b>TO-220</b>  
<p><b>Features:</b></p> <ul style="list-style-type: none"> <li><input type="checkbox"/> Low Intrinsic Capacitances.</li> <li><input type="checkbox"/> Excellent Switching Characteristics.</li> <li><input type="checkbox"/> Extended Safe Operating Area.</li> <li><input type="checkbox"/> Unrivalled Gate Charge :<math>Q_g=15nC</math> (Typ.).</li> <li><input type="checkbox"/> <math>BVDSS=700V, I_D=4A</math></li> <li><input type="checkbox"/> <math>R_{DS(on)}:3.3\Omega</math> (Max) @<math>V_G=10V</math></li> <li><input type="checkbox"/> 100% Avalanche Tested</li> </ul>	 <p>1. Gate (G) 2. Drain (D) 3. Source (S)</p>

### Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	700	V
$I_D$	Drain Current	$T_j=25^\circ C$	4.0
		$T_j=100^\circ C$	2.3
$V_{GS(TH)}$	Gate Threshold Voltage	$\pm 30$	V
$E_{AS}$	Single Pulse Avalanche Energy (note1)	300	mJ
$I_{AR}$	Avalanche Current (note2)	4	A
$P_D$	Power Dissipation ( $T_j=25^\circ C$ )	30	W
$T_j$	Junction Temperature(Max)	150	°C
$T_{stg}$	Storage Temperature	-55~+150	°C
$T_L$	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	4.16	°C/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	-	62.5	°C/W

**Electrical Characteristics** (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0	700	-	-	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =250μA, Reference to 25°C	-	0.6	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =700V, V <sub>GS</sub> =0V	-	-	1	μA
		V <sub>DS</sub> =560V, T <sub>j</sub> =125°C			10	
I <sub>GSSF</sub>	Gate-body leakage Current, Forward	V <sub>GS</sub> =+30V, V <sub>DS</sub> =0V	-	-	100	nA
I <sub>GSSR</sub>	Gate-body leakage Current, Reverse	V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V	-	-	-100	
<b>On Characteristics</b>						
V <sub>GS(TH)</sub>	Date Threshold Voltage	I <sub>D</sub> =250μA, V <sub>DS</sub> =V <sub>GS</sub>	2	-	4	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	I <sub>D</sub> =2.0A, V <sub>GS</sub> =10V	-	3.0	3.3	Ω
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0, f=1.0MHz	-	440	560	pF
C <sub>oss</sub>	Output Capacitance		-	65	85	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	5.6	7.3	
<b>Switching Characteristics</b>						
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =350V, I <sub>D</sub> =4A R <sub>G</sub> =25Ω (Note 3,4)	-	13	35	ns
T <sub>r</sub>	Turn-On Rise Time		-	45	110	
T <sub>d(off)</sub>	Turn-Off Delay Time		-	25	60	
T <sub>f</sub>	Turn-Off Rise Time		-	35	80	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =480V, V <sub>GS</sub> =10V, I <sub>D</sub> =4A (Note 3,4)	-	15	20	nC
Q <sub>gs</sub>	Gate-Source Charge		-	3.4	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	7.1	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>s</sub>	Max. Diode Forward Current	-	-	-	4	A
I <sub>SM</sub>	Max. Pulsed Forward Current	-	-	-	16	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>D</sub> =4A	-	-	1.4	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>s</sub> =4A, V <sub>GS</sub> =0V diF/dt=100A/μs (Note3)	-	250	-	nS
Q <sub>rr</sub>	Reverse Recovery Charge		-	1.5	-	μC

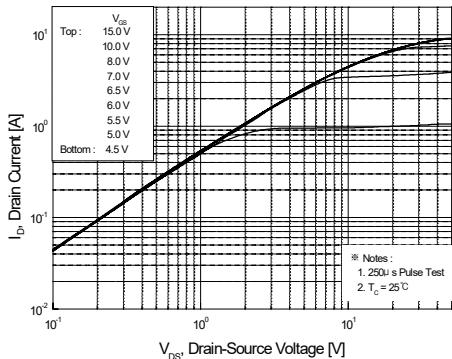
Notes : 1, L=0.5mH, IAS=4A, VDD=50V, RG=25Ω, Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

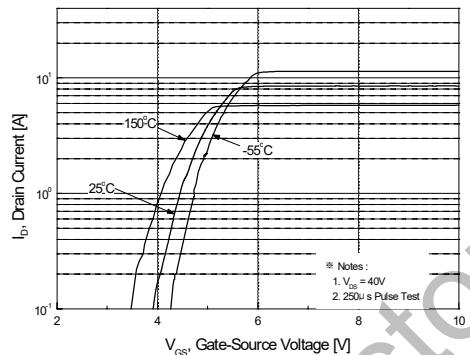
3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

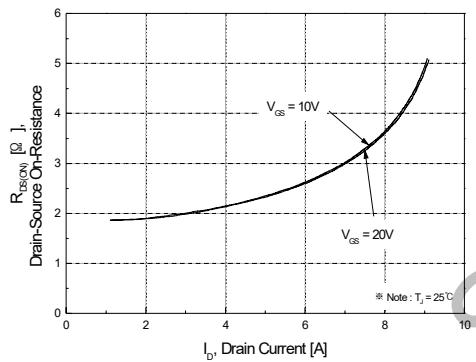
## Typical Characteristics



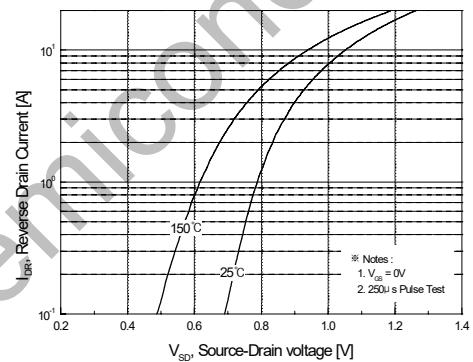
**Figure 1. On-Region Characteristics**



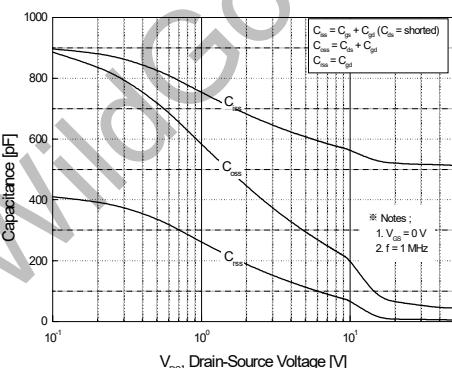
**Figure 2. Transfer Characteristics**



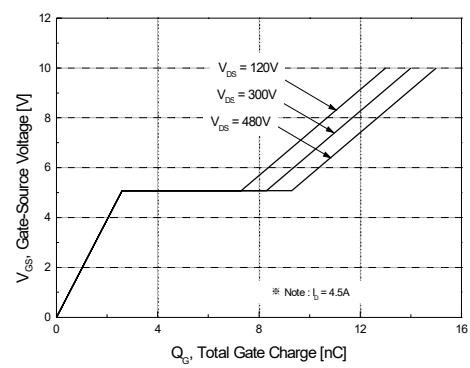
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

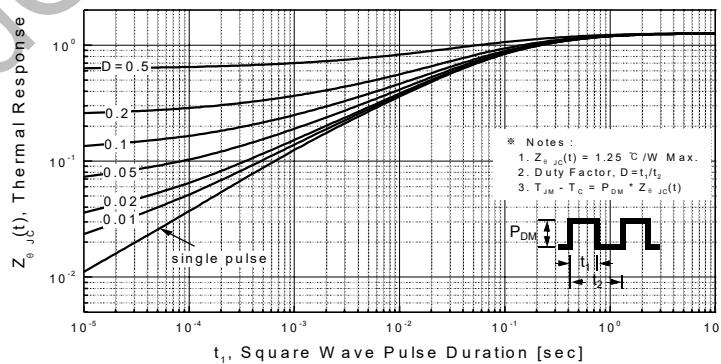
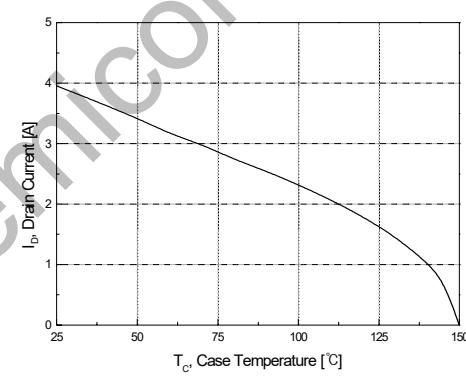
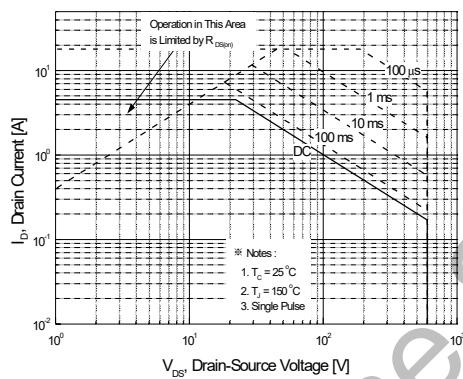
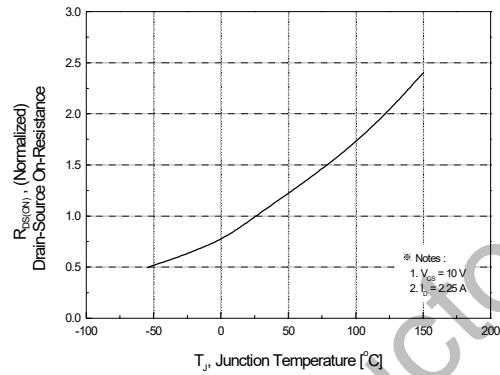
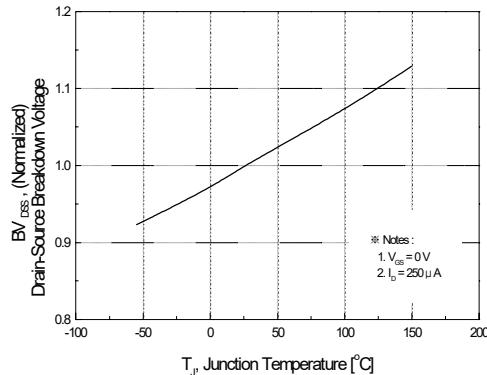


**Figure 5. Capacitance Characteristics**

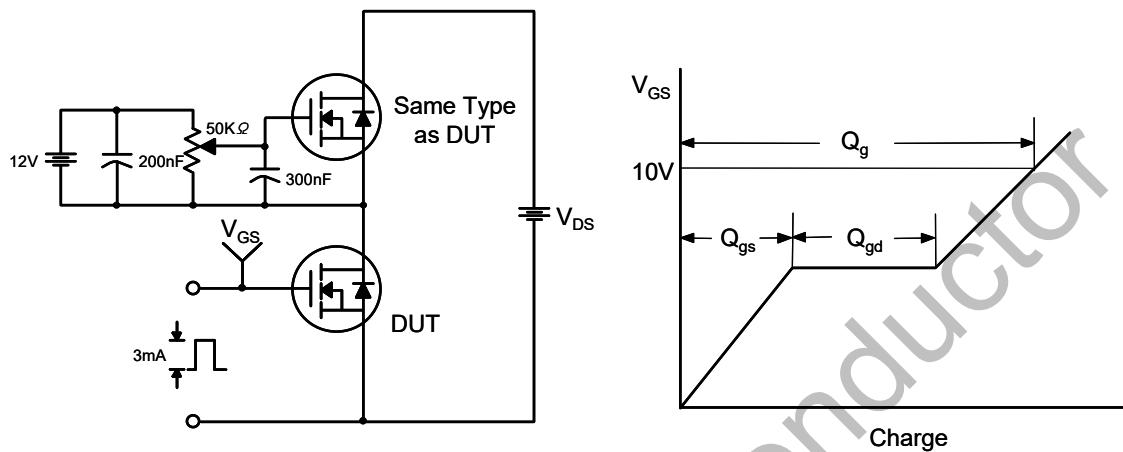


**Figure 6. Gate Charge Characteristics**

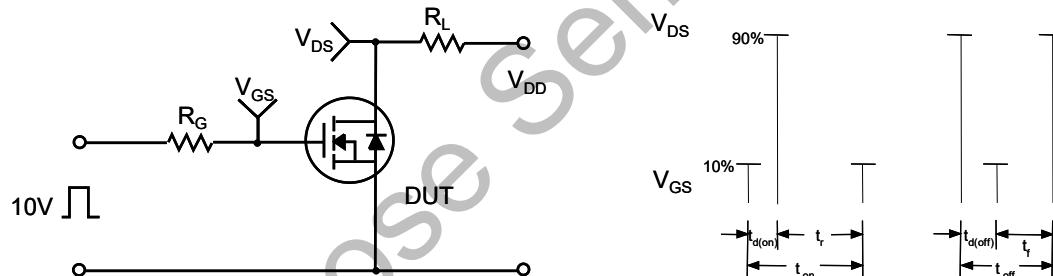
## Typical Characteristics (Continued)



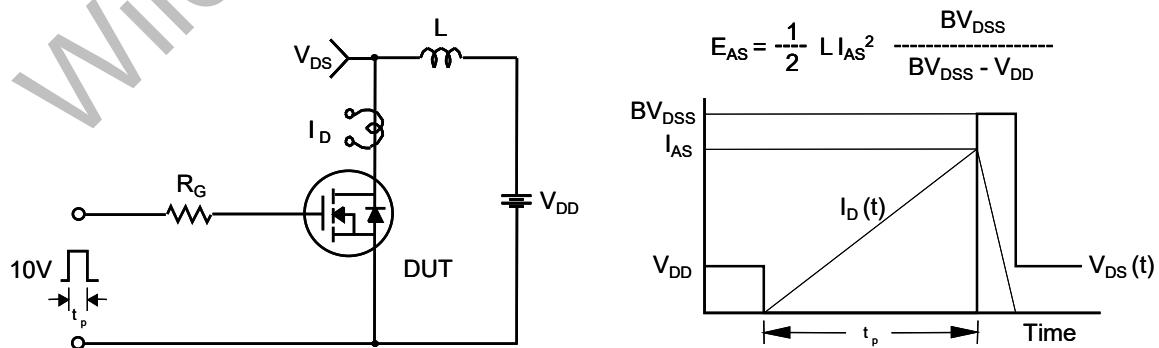
Gate Charge Test Circuit &amp; Waveform



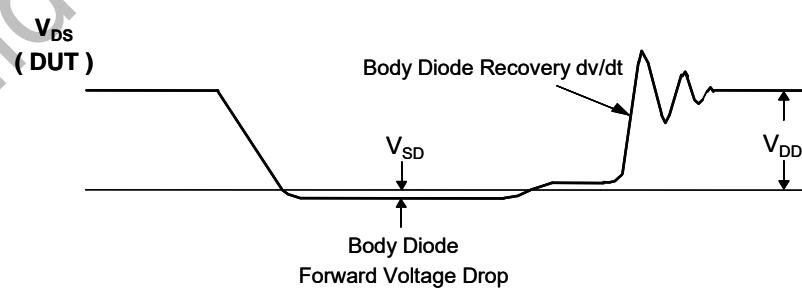
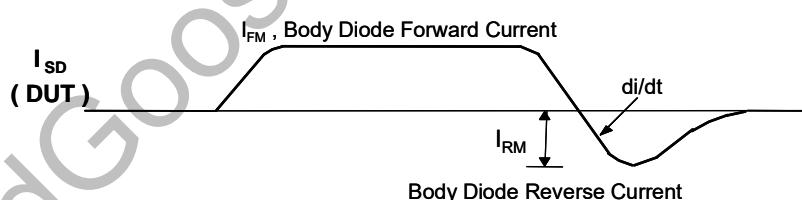
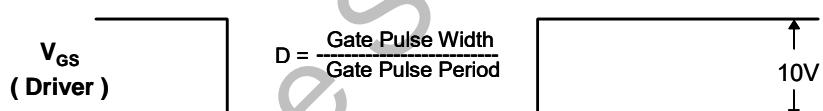
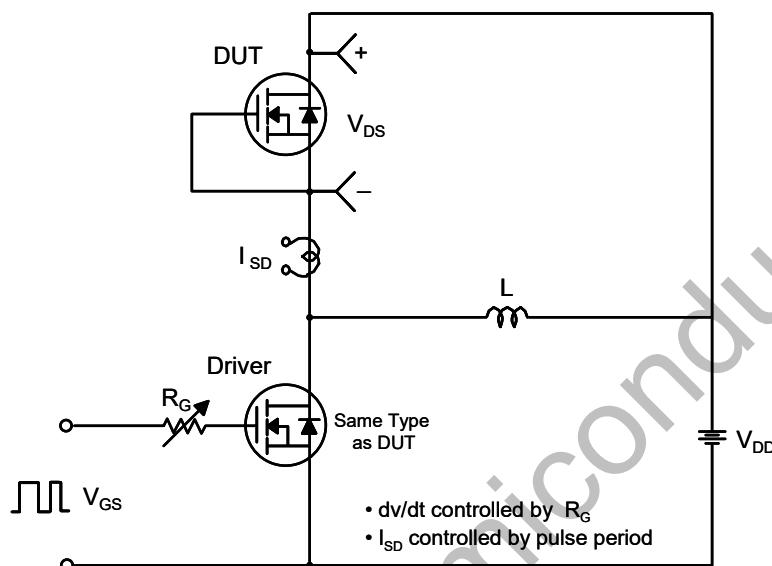
Resistive Switching Test Circuit &amp; Waveforms



Unclamped Inductive Switching Test Circuit &amp; Waveforms

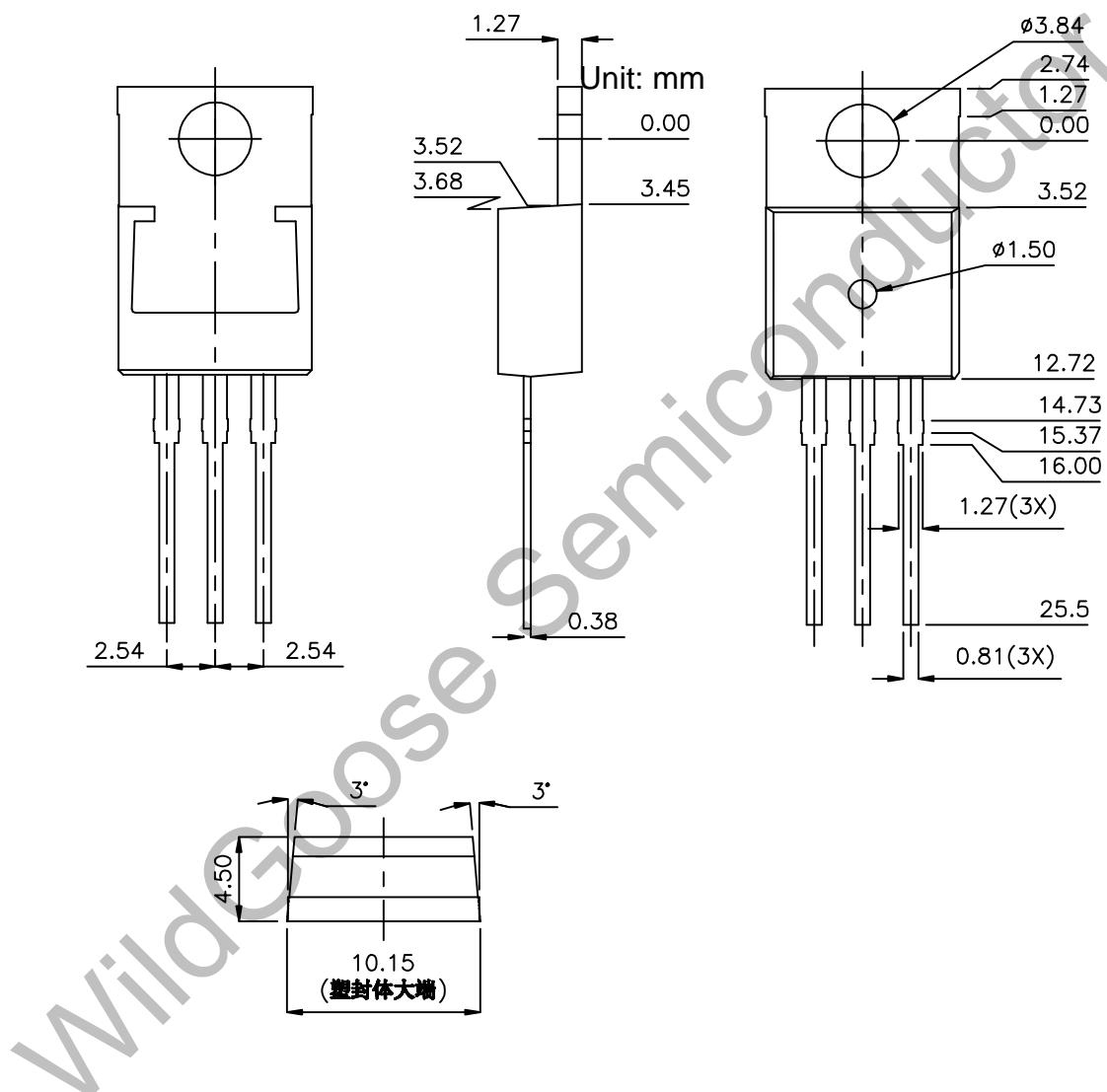


## Peak Diode Recovery dv/dt Test Circuit &amp; Waveforms



## Package Dimension

TO-220



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